SUPPLEMENT NO. 7 TO PART 748 - AUTHORIZATION VALIDATED END-USER (VEU): LIST OF VALIDATED END-USERS, RESPECTIVE ITEMS ELIGIBLE FOR EXPORT, REEXPORT AND TRANSFER, AND ELIGIBLE DESTINATIONS

Country	Validated End-User	Eligible Items (By ECCN)	Eligible Destination	Federal Register Citation
No	thing in this Supp	lement shall be deemed to supersede other prov	visions in the EAR, including but not limited to § 748.1	5(c).
China (People's Republic of)	Advanced Micro Devices China, Inc. 3D002, 3D003, 3E001 ("technology" for items of 3C002 and 3C004 and "during the International Roadmap for Semicondur process for items classiff 3B001 and 3B002), 3E0 ("technology" for use during the International Roadmap for Semicondur process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0 ("development" and "process for items classiff 3B001 and 3B002), 3E0	3D002, 3D003, 3E001 (limited to "technology" for items classified under 3C002 and 3C004 and "technology" for use during the International Technology Roadmap for Semiconductors (ITRS) process for items classified under ECCNs 3B001 and 3B002), 3E002 (limited to "technology" for use during the ITRS process for items classified under ECCNs 3B001 and 3B002), 3E003.e (limited to the "development" and "production" of integrated circuits for commercial applications), 4D001, 4D002 and 4E001 (limited to the "development" of products under ECCN 4A003).	AMD Technologies (China) Co., Ltd., No. 88, Su Tong Road, Suzhou, China 215021. Advanced Micro Devices (Shanghai) Co., Ltd. Buildings 46, 47, 48 & 49, River Front Harbor, Zhangjiang Hi-Tech Park 1387 Zhangdong Rd., Pudong, Shanghai, China 201203. AMD Technology Development (Beijing) Co., Ltd. North and South Buildings RaycomInfotech, Park Tower C, No. 2 Science Institute South Rd., Zhong Guan Cun, Haidian District, Beijing, China 100190. AMD Products (China) Co. Ltd. North and South Buildings	75 FR 25763, 5/10/10. 76 FR 2802, 1/18/11. 78 FR 3319, 1/16/13.
	Applied Materials (China), Inc.	2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.c, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to "software" specially designed for the "use" of stored program controlled items classified under ECCN 3B001).	RaycomInfotech Park Tower C, No. 2 Science Institute South Rd., Zhong Guan Cun, Haidian District, Beijing, China 100190. Applied Materials South East Asia Pte. Ltd Shanghai Depot c/o Shanghai Applied Materials Technical Service Center No. 2667 Zuchongzhi Road, Shanghai, China 201203.	72 FR 59164, 10/19/07. 74 FR 19382, 4/29/09. 75 FR 27185,

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Nothin	ng in this Supp	lement shall be deemed to supersede other prov	isions in the EAR, including but not limited to § 748.13	
Nothir	ng in this Supp	lement shall be deemed to supersede other prov	Applied Materials South East Asia Pte. Ltd Beijing Depot c/o Beijing Applied Materials Technical Service Center No. 1 North Di Sheng Street, BDA Beijing, China 100176. Applied Materials South East Asia Pte. Ltd Wuxi Depot c/o Sinotrans Jiangsu Fuchang Logistics Co., Ltd. 1 Xi Qin Road, Wuxi Export Processing Zone Wuxi, Jiangsu, China 214028. Applied Materials South East Asia Pte. Ltd Wuhan Depot c/o Wuhan Optics Valley Import & Export Co., Ltd. No. 101 Guanggu Road East Lake High-Tec Development Zone Wuhan, Hubei, China 430074. Applied Materials (China), Inc Shanghai Depot No. 2667, Zuchongzhi Road Shanghai, China 201203. Applied Materials (China), Inc Beijing Depot No. 1 North Di Sheng Street, BDA Beijing, China 100176.	5(c). 5/14/10. 77 FR 10953, 2/24/12.

Country	Validated End-User	Eligible Items (By ECCN)	Eligible Destination	Federal Register Citation
Not	thing in this Supp	lement shall be deemed to supersede other prov	isions in the EAR, including but not limited to § 748.1	5(c).
	Boeing Tianjin Composites Co. Ltd.	2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.c, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to "software" specially designed for the "use" of stored program controlled items classified under ECCN 3B001), and 3E001 (limited to "technology" according to the General Technology Note for the "development" or "production" of items controlled by ECCN 3B001). 1B001.f, 1D001 (limited to "software" specially designed or modified for the "use" of equipment controlled by 1B001.f), 2B001.b.2 (limited to machine tools with accuracies no better than (<i>i.e.</i> , not less than) 13 microns), 2D001 (limited to "software," other than that controlled by 2D002, specially designed or modified for the "use" of equipment controlled by 2B001.b.2), and 2D002 (limited to "software" for electronic devices, even when residing in an electronic devices, even when residing such devices or systems to function as a "numerical control" unit, capable of coordinating simultaneously	Applied Materials (Xi'an) Ltd. No. 28 Xin Xi Ave., Xi'an High Tech Park Export Processing Zone Xi'an, Shaanxi, China 710075. Boeing Tianjin Composites Co. Ltd. No. 4-388 Heibei Road Tanggu Tianjin, China.	72 FR 59164, 10/19/07. 74 FR 19382, 4/29/09. 77FR 10953, 2/24/12. 77 FR 40258, 7/9/12.
		more than 4 axes for "contouring control" controlled by 2B001.b.2).		
	CSMC	1C350.c.3, 1C350.c.11, 2B230.a, 2B230.b,	CSMC Technologies Fab 1 Co., Ltd.	76 FR 2802,
	Technologies Corporation	2B350.f, 2B350.g, 2B350.h, 3B001.c.1.a, 3B001.c.2.a, 3B001.e 3B001.h (except for	14 Liangxi Road Wuxi, Jiangsu 214061, China.	1/18/11. 76 FR 37634,

Country	Validated End-User	Eligible Items (By ECCN)	Eligible Destination	Federal Register Citation		
No	Nothing in this Supplement shall be deemed to supersede other provisions in the EAR, including but not limited to § 748.15(c).					
		multilayer masks with a phase shift layer designed to produce "space qualified" semiconductor devices), 3C002.a, and 3C004.	CSMC Technologies Fab 2 Co., Ltd. 8 Xinzhou Rd. Wuxi National New Hi-Tech Industrial Development Zone Wuxi, Jiangsu 214028, China.	6/28/11. 77 FR 10953, 2/24/12. 78 FR 23472, 4/19/13.		
	Grace Semiconductor Manufacturing Corporation.	1C350.c.3, 1C350.d.7, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.4, 3B001.a.1, 3B001.b, 3B001.c, 3B001.e, 3B001.f, 3B001.h, 3C002, 3C004, 5B002, and 5E002 (limited to production technology for integrated circuits controlled by ECCNs 5A002 or 5A992 that have been successfully reviewed under the encryption review process specified in sections 740.17(b)(2) or 740.17(b)(3) and 742.15 of the EAR; Note also the guidance on cryptographic interfaces (OCI) in section 740.17(b) of the EAR).	1399 Zuchongzhi Road Zhangjiang Hi-Tech Park Shanghai, PR China 201203.	75 FR 2435, 1/15/10.		
	Lam Research Corporation	These Items Authorized for those Lam's Destinations Identified by a single asterisk (*): 2B230, 2B350.c, 2B350.d, 2B350.g, 2B350.h, 2B350.i, 3B001.c and 3B001.e (items classified under ECCNs 3B001.c and 3B001.e are limited to specially designed components and accessories), 3D001 (limited to "software" (excluding source code) specially designed for the "development" or "production" of equipment controlled by	*Lam Research International Sarl (Lam Shanghai Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd. No. 3869, Longdong Avenue Pudong New District Shanghai, China 201203. *Lam Research International Sarl (Lam Shanghai Warehouse; WGQ Bonded Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd. No. 55, Fei la Road, Waigaoqiao Free Trade Zone Pudong New Area Shanghai, China 200131.	75 FR 62462, 10/12/10. 77 FR 10953, 2/24/12. 78 FR 3319, 1/16/13.		

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		ECCN 3B001), 3D002 (limited to	*Lam Research International Sarl (Lam Beijing	
		"software" (excluding source code) specially	Warehouse)	
		designed for the "use" of equipment	c/o Beijing Lam Electronics Tech Center, No. 8	
		controlled by ECCN 3B001), and 3E001	Building	
		(limited to "technology" according to the	No. 1, Disheng North Street, Beijing Economic &	
		General Technology Note for the	Technological Development Area	
		"development" of equipment controlled by	Beijing, China 100176.	
		ECCN 3B001)	*Lam Research International Sarl (Wuxi EPZ	
			Bonded Warehouse)	
			c/o HMG WHL Logistic (Wuxi) Co., Ltd.	
			1st Fl, Area 4, No. 1, Plot J3	
			No. 5 Gaolang East Road	
			Export Processing Zone	
			Wuxi, China 214028.	
			*Lam Research International Sarl (Lam Beijing	
			Warehouse)	
			c/o HMG Hi-tech Logistics (Beijing) Co., Ltd.	
			Building 3, No. 9 Ke Chuang Er Street	
			Beijing Economic Technological Development	
			Area	
			Beijing, China 100176.	
			*Lam Research International Sarl (Wuhan TSS)	
			c/o HMG Wuhan Logistic Co., Ltd.	
			1st-2nd Floor, Area B, No. 5 Building	
			Hua Shi Yuan Er Road	
			East-lake Hi-Tech Development Zone	
			Wuhan, Hubei Province, China 430223.	

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No	thing in this Supp	lement shall be deemed to supersede other provi	isions in the EAR, including but not limited to § 748.15	5(c).
		These Items Authorized for those Lam's	**Lam Research Service Co., Ltd.	
		Destinations Identified by two asterisks (**):	1st Floor, Area C	
		2B230, 2B350.c, 2B350.d, 2B350.g,	Hua Hong Science & Technology Park	
		2B350.h, 2B350.i, 3B001.c and 3B001.e	177 Bi Bo Road	
		(items classified under ECCNs 3B001.c and	Zhangjiang Hi-Tech Park	
		3B001.e are limited to specially designed	Pudong, Shanghai, China 201203.	
		components and accessories), 3D001 (limited	**Lam Research (Shanghai) Co., Ltd.	
		to "software" (excluding source code)	No. 1 Jilong Rd.	
		specially designed for the "development" or	Room 424-2	
		"production" of equipment controlled by	Waigaoqiao Free Trade Zone	
		ECCN 3B001), 3D002 (limited to "software"	Shanghai, China 200131.	
		(excluding source code) specially designed	**Lam Research Service Co., Ltd. (Beijing Branch)	
		for the "use" of equipment controlled by ECCN 3B001), and 3E001 (limited to	Rm 1010, Zhaolin Building	
		"technology" according to the General	No. 15 Rong Hua Zhong Road	
		Technology Note for the "development" or	Beijing Economic & Technological Development	
		"production" (limited to those stages that	Area	
		support integration, assembly (mounting),	Beijing, China 100176.	
		inspection, testing, and quality assurance) of	**Lam Research Service Co., Ltd.	
		equipment controlled by ECCN 3B001).	Wuxi Representative Office	
		equipment controlled by Ecciv 32001).	Room 302, Building 6, Singapore International Park No. 89 Xing Chuang Si Road	
			Wuxi New District	
			Wuxi, Jiangsu, China 214028.	
			**Lam Research Service Co., Ltd.	
			Wuhan Representative Office	
			Room 302, Guanggu Software Park Building E4	
			No. 1 Guanshan Road	
			Donghu Development Zone	
			Wuhan, Hubei Province, China 430074.	

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No	thing in this Supp	lement shall be deemed to supersede other prov	isions in the EAR, including but not limited to § 748.1	5(c).
	Semiconductor Manufacturing International Corporation	1C350.c.3, 1C350.d.7, 2B006.b.1, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.3, 3B001.a, 3B001.b, 3B001.c, 3B001.e, 3B001.f, 3C001, 3C002, 3C004, 5B002, and 5E002 (limited to "technology" according to the General Technology Note for the "production" of integrated circuits controlled by ECCN 5A002 that have been classified by BIS as eligible for License Exception ENC under paragraph (b)(2) or (b)(3) of section 740.17 of the EAR, or classified by BIS as a mass market item under paragraph (b)(3) of section 742.15 of the EAR).	**Lam Research Semiconductor (Suzhou) Co., Ltd. (Suzhou) A Division of Lam Research International Sarl A-2 Building, Export Processing Zone Suzhou New District Jiangsu Province, China 215151. Semiconductor Manufacturing International (Shanghai) Corporation 18 Zhang Jiang Rd., Pudong New Area Shanghai, China 201203. Semiconductor Manufacturing International (Tianjin) Corporation 19 Xing Hua Avenue Xi Qing Economic Development Area Tianjin, China 300385. Semiconductor Manufacturing International (Beijing) Corporation, No. 18 Wen Chang Road Beijing Economic-Technological Development Area Beijing, China 100176.	72 FR 59164, 10/19/07. 75 FR 67029, 11/1/10. 77 FR 10953, 2/24/12.
	Shanghai Hua Hong NEC Electronics Company, Ltd.	1C350.c.3, 1C350.d.7, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.4, 3B001.c.2, 3C002, and 3C004.	Headquarters and Fab. 1 of HHNEC No. 1188 Chuan Qiao Rd. Pu Dong, Shanghai, China 201206. Fab. 2 of HHNEC No. 668 Guo Shou Jing Rd. Zhang Jiang High Tech Park Pu Dong, Shanghai, China 201203.	72 FR 59164, 10/19/07.
	SK hynix Semiconductor (China) Ltd.	3B001.a, 3B001.b, 3B001.c, 3B001.e, and 3B001.f.	SK hynix Semiconductor (China) Ltd. Lot K7/K7-1, Export Processing Zone Wuxi, Jiangsu, China 214028.	75 FR 62462, 10/12/10. 77 FR 40258,

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No	thing in this Supp	lement shall be deemed to supersede other prov	risions in the EAR, including but not limited to § 748.1	5(c).
				7/9/12. 78 FR 3319, 1/16/13.
	SK hynix Semiconductor (Wuxi) Ltd.	3B001.a, 3B001.b, 3B001.c, 3B001.e, and 3B001.f.	SK hynix Semiconductor (Wuxi) Ltd., Lot K7/K7–1, Export Processing Zone, Wuxi, Jiangsu, China 214028.	75 FR 62462, 10/12/10. 77 FR 40258, 7/9/12. 78 FR 3319, 1/16/13.
India	GE India Industrial Pvt Ltd.	1C002.a.1, 1C002.a.2, 1C002.b.1.a, 1C002.b.1.b, 1E001, 2E003.f, 9E003.a.1, 9E003.a.2, 9E003.a.4, 9E003.a.5, 9E003.a.6, 9E003.a.8, and 9E003.c.	GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India. Bangalore Engineering Center (BEC) c/o GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India.	74 FR 31620, 7/2/09. 74 FR 68147, 12/23/09. 77 FR 10953, 2/24/12.